Dual 2-Input AND Gate

The NL27WZ08 is a high performance dual 2-input AND Gate operating from a 1.65 V to 5.5 V supply.

- Extremely High Speed: t_{PD} 2.5 ns (typical) at $V_{CC} = 5 V$
- Designed for 1.65 V to 5.5 V V_{CC} Operation
- Over Voltage Tolerant Inputs
- LVTTL Compatible Interface Capability With 5 V TTL Logic with V_{CC} = 3 V
- LVCMOS Compatible
- 24 mA Balanced Output Sink and Source Capability
- Near Zero Static Supply Current Substantially Reduces System Power Requirements
- Replacement for NC7WZ08
- Chip Complexity: FET = 124

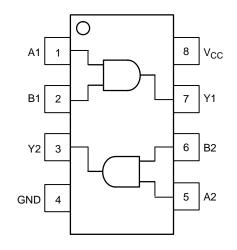


Figure 1. Pinout

PIN ASSIGNMENT

Pin	Function
1	A1
2	B1
3	Y2
4	GND
5	A2
6	B2
7	Y1
8	V _{CC}

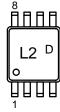


ON Semiconductor®

http://onsemi.com

MARKING DIAGRAM

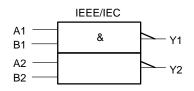




D = Date Code

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 4 of this data sheet.





FUNCTION TABLE

ľ	=	AB	

Inp	Output	
Α	В	Y
L	L	L
L	Н	L
Н	L	L
Н	Н	Н

H = HIGH Logic Level

L = LOW Logic Level

MAXIMUM RATINGS

Symbol	Pa	rameter	Value	Unit
V _{CC}	DC Supply Voltage		-0.5 to +7.0	V
VI	DC Input Voltage		-0.5 to +7.0	V
Vo	DC Output Voltage		-0.5 to V _{CC} + 0.5	V
I _{IK}	DC Input Diode Current	V ₁ < GND	-50	mA
I _{OK}	DC Output Diode Current	V _O < GND	-50	mA
I _O	DC Output Sink Current		±50	mA
I _{CC}	DC Supply Current per Supply Pin		±100	mA
I _{GND}	DC Ground Current per Ground Pin		±100	mA
T _{STG}	Storage Temperature Range		-65 to +150	°C
TL	Lead Temperature, 1 mm from Case for	10 Seconds	260	°C
TJ	Junction Temperature under Bias		+ 150	°C
θ_{JA}	Thermal Resistance	(Note 1)	250	°C/W
PD	Power Dissipation in Still Air at 85°C		250	mW
MSL	Moisture Sensitivity		Level 1	
F _R	Flammability Rating	Oxygen Index: 28 to 34	UL 94 V–0 @ 0.125 in	
V _{ESD}	ESD Withstand Voltage	Human Body Model (Note 2) Machine Model (Note 3) Charged Device Model (Note 4)	> 2000 > 200 N/A	V
I _{Latch-Up}	Latch–Up Performance	Above V_{CC} and Below GND at 85°C (Note 5)	±500	mA

Maximum Ratings are those values beyond which damage to the device may occur. Exposure to these conditions or conditions beyond those indicated may adversely affect device reliability. Functional operation under absolute maximum-rated conditions is not implied. Functional operation should be restricted to the Recommended Operating Conditions.

1. Measured with minimum pad spacing on an FR4 board, using 10 mm-by-1 inch, 2-ounce copper trace with no air flow.

Tested to EIA/JESD22–A114–A.
 Tested to EIA/JESD22–A115–A.

4. Tested to JESD22-C101-A.

5. Tested to EIA/JESD78.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Max	Unit	
V _{CC}	Supply Voltage	Operating Data Retention Only	1.65 1.5	5.5 5.5	V
VI	Input Voltage	(Note 6)	0	5.5	V
Vo	Output Voltage	(HIGH or LOW State)	0	V _{CC}	V
T _A	Operating Free–Air Temperature		-40	+ 85	°C
$\Delta t / \Delta V$	Input Transition Rise or Fall Rate	$V_{CC} = 2.5 V \pm 0.2 V V_{CC} = 3.0 V \pm 0.3 V V_{CC} = 5.0 V \pm 0.5 V$	0 0 0	20 10 5	ns/V

6. Unused inputs may not be left open. All inputs must be tied to a high- or low-logic input voltage level.

DC ELECTRICAL CHARACTERISTICS

			Vcc	Т	_A = 25°0	2	-40°C ≤ .		
Symbol	Parameter	Condition	(V)	Min	Тур	Max	Min	Max	Unit
V _{IH}	High–Level Input Voltage		1.65 2.3 to 5.5	0.75 V _{CC} 0.7 V _{CC}			0.75 V _{CC} 0.7 V _{CC}		V
V _{IL}	Low-Level Input Voltage		1.65 2.3 to 5.5			0.25 V _{CC} 0.3 V _{CC}		0.25 0.3 V _{CC}	V
V _{OH}	High–Level Output Voltage $V_{IN} = V_{IL}$ or V_{IH}	$\begin{split} I_{OH} &= 100 \ \mu A \\ I_{OH} &= -3 \ m A \\ I_{OH} &= -8 \ m A \\ I_{OH} &= -12 \ m A \\ I_{OH} &= -16 \ m A \\ I_{OH} &= -24 \ m A \\ I_{OH} &= -32 \ m A \end{split}$	1.65 to 5.5 165 2.3 2.7 3.0 3.0 4.5	V _{CC} - 0.1 1.29 1.9 2.2 2.4 2.3 3.8	V _{CC} 1.5 2.1 2.4 2.7 2.5 4.0		V _{CC} - 0.1 1.5 1.9 2.2 2.4 2.3 3.8		V
V _{OL}	Low–Level Output Voltage $V_{IN} = V_{IH}$ or V_{OH}	$I_{OL} = 100 \ \mu A$ $I_{OL} = 3 \ mA$ $I_{OL} = 8 \ mA$ $I_{OL} = 12 \ mA$ $I_{OL} = 16 \ mA$ $I_{OL} = 24 \ mA$ $I_{OL} = 32 \ mA$	1.65 to 5.5 2.3 2.7 3.0 3.0 4.5		0.08 0.20 0.22 0.28 0.38 0.42	0.1 0.24 0.3 0.4 0.4 0.55 0.55		0.1 0.24 0.3 0.4 0.4 0.55 0.55	V
I _{IN}	Input Leakage Current	$V_{IN} = V_{CC}$ or GND	0 to 5.5			±0.1		±1.0	μA
I _{CC}	Quiescent Supply Current	$V_{IN} = V_{CC} \text{ or } GND$	5.5			1.0		10	μA

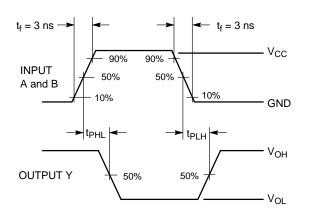
AC ELECTRICAL CHARACTERISTICS t_{R} = t_{F} = 3.0 ns

			V _{CC}	•	T _A = 25°C	;	-40°C ≤ -	Γ _A ≤ 85°C	
Symbol	Parameter	Condition	(V)	Min	Тур	Max	Min	Max	Unit
t _{PLH}	Propagation Delay	R_L = 1 M Ω , C_L = 15 pF	$1.8~\pm~0.15$	2.0	5.7	10.5	2.0	11.0	ns
t _{PHL}	(Figure 3 and 4)		2.5 ± 0.2	1.0	3.5	5.8	2.0	6.2	
		$ \begin{array}{l} R_{L} = 1 \; M\Omega, C_{L} = 15 \; pF \\ R_{L} = 500 \; \Omega, C_{L} = 50 \; pF \end{array} $	3.3 ± 0.3	0.8 1.2	2.6 3.2	3.9 4.8	0.8 1.2	4.3 5.2	
		$ \begin{array}{l} R_{L} = 1 \; M\Omega, C_{L} = 15 \; pF \\ R_{L} = 500 \; \Omega, C_{L} = 50 \; pF \end{array} $	5.0 ± 0.5	0.5 0.8	1.9 2.5	3.1 3.7	0.5 0.8	3.3 4.0	

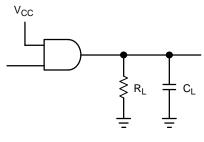
CAPACITIVE CHARACTERISTICS

Symbol	Parameter	Condition	Typical	Unit
C _{IN}	Input Capacitance	V_{CC} = 5.5 V, V_{I} = 0 V or V_{CC}	4	pF
C _{PD}	Power Dissipation Capacitance (Note 7)	10 MHz, V _{CC} = 3.3 V, V _I = 0 V or V _{CC} 10 MHz, V _{CC} = 5.5 V, V _I = 0 V or V _{CC}	25 30	pF

7. C_{PD} is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation: $I_{CC(OPR)} = C_{PD} \bullet V_{CC} \bullet f_{in} + I_{CC}$. C_{PD} is used to determine the no–load dynamic power consumption; $P_D = C_{PD} \bullet V_{CC}^2 \bullet f_{in} + I_{CC} \bullet V_{CC}$.







A 1–MHz square input wave is recommended for propagation delay tests.



DEVICE ORDERING INFORMATION

	Device Nomenclature							
Device Order Number	Logic Circuit Indicator	No. of Gates per Package	Temp Range Identifier	Technology	Device Function	Package Suffix	Package Type	Tape and Reel Size
NL27WZ08US	NL	2	7	WZ	08	US	US8	178 mm, 3000 Unit

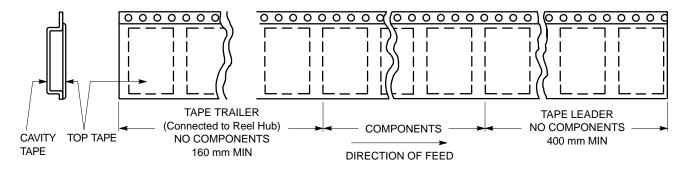


Figure 5. Tape Ends for Finished Goods

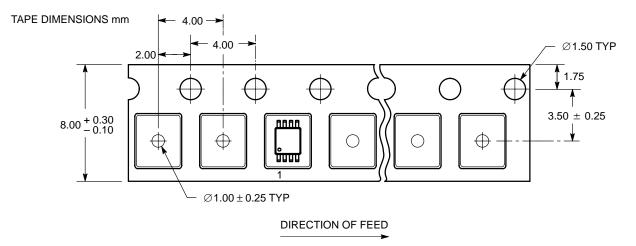
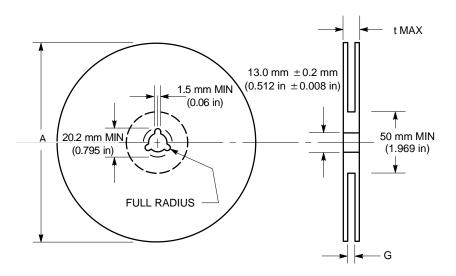


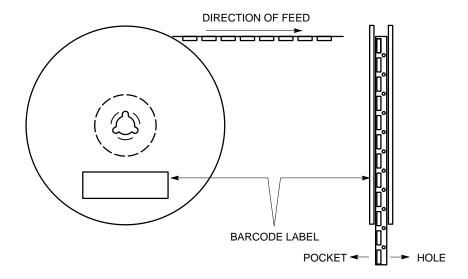
Figure 6. US8 Reel Configuration/Orientation





REEL DIMENSIONS

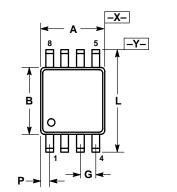
Tape Size	T and R Suffix	A Max	G	t Max
8 mm	US	178 mm (7 in)	8.4 mm, + 1.5 mm, –0.0 (0.33 in + 0.059 in, –0.00)	14.4 mm (0.56 in)





PACKAGE DIMENSIONS

US8 **US SUFFIX** CASE 493-01 ISSUE O



-T-

SEATING PLANE

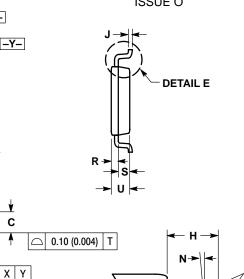
D

 \oplus

0.10 (0.004) 🔘

С ¥

Т



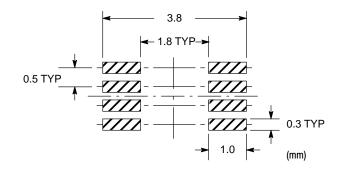
R 0.10 TYP

Μ

F ≻

- NOTES: 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: MILLIMETERS 3. DIMENSION 'A" DOES NOT INCLUDE MOLD FLASH, PROTRUSION OR GATE BURR. MOLD FLASH, PROTRUSION OR GATE BURR SHALL NOT EXCEED 0.140 MM (0.0055') PER SIDE. 4. DIMENSION 'B' DOES NOT INCLUDE INTER-LEAD FLASH OR PROTRUSION. INTER-LEAD FLASH AND PROTRUSION. SHALL NOT E3XCEED 0.140 (0.0055') PER SIDE. 5. LEAD FINISH IS SOLDER PLATING WITH THICKNESS OF 0.0076-0.0203 MM. (300-800 INCH).
- INCH). 6. ALL TOLERANCE UNLESS OTHERWISE SPECIFIED ±0.0508 (0.0002").

	MILLIN	IETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α	1.90	2.10	0.075	0.083
В	2.20	2.40	0.087	0.094
С	0.60	0.90	0.024	0.035
D	0.17	0.25	0.007	0.010
F	0.20	0.35	0.008	0.014
G	0.50	BSC	0.020) BSC
Η	0.40	REF	0.016 REF	
ſ	0.10	0.18	0.004	0.007
K	0.00	0.10	0.000	0.004
L	3.00	3.20	0.118	0.126
Μ	0 °	6 °	0 °	6 °
Ν	5 °	10 °	5 °	10 °
Ρ	0.28	0.44	0.011	0.017
R	0.23	0.33	0.009	0.013
S	0.37	0.47	0.015	0.019
U	0.60	0.80	0.024	0.031
۷	0.12	BSC	0.005	5 BSC



DETAIL E

4

ON Semiconductor and **W** are registered trademarks of Semiconductor Components Industries, LLC (SCILLC). SCILLC reserves the right to make changes without further notice to any products herein. SCILLC makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does SCILLC assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. "Typical" parameters which may be provided in SCILLC data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. SCILLC does not convey any license under its patent rights nor the rights of others. SCILLC products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the SCILLC product could create a situation where personal injury or death may occur. Should Buyer purchase or use SCILLC products for any such unintended or unauthorized application, Buyer shall indemnify and hold SCILLC and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death wits such unintended or unauthorized use, even if such claim alleges that SCILLC was negligent regarding the design or manufacture of the part. SCILLC is an Equal Opportunity/Affirmative Action Employer.

PUBLICATION ORDERING INFORMATION

Literature Fulfillment:

Literature Distribution Center for ON Semiconductor

P.O. Box 5163, Denver, Colorado 80217 USA

Phone: 303–675–2175 or 800–344–3860 Toll Free USA/Canada Fax: 303–675–2176 or 800–344–3867 Toll Free USA/Canada Email: ONlit@hibbertco.com

N. American Technical Support: 800-282-9855 Toll Free USA/Canada

JAPAN: ON Semiconductor, Japan Customer Focus Center 4–32–1 Nishi–Gotanda, Shinagawa–ku, Tokyo, Japan 141–0031 Phone: 81–3–5740–2700 Email: r14525@onsemi.com

ON Semiconductor Website: http://onsemi.com

For additional information, please contact your local Sales Representative.